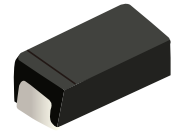


## FEATURES

- | Glass Passivated Die Construction
- | Fast Recovery Time for High Efficiency
- | Low reverse leakage
- | Ideally Suited for Automatic Assembly



DO-214AC(SMA)



Schematic Symbol

## MECHANICAL DATA

- | Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- | Moisture Sensitivity: Level 1 per J-STD-020

## APPROVALS

<b>RoHS</b>	Compliance with 2011/65/EU
<b>HF</b>	Compliance with IEC61249-2-21:2003

## MAXIMUM RATINGS AND CHARACTERISTICS (T<sub>A</sub>=25°C)

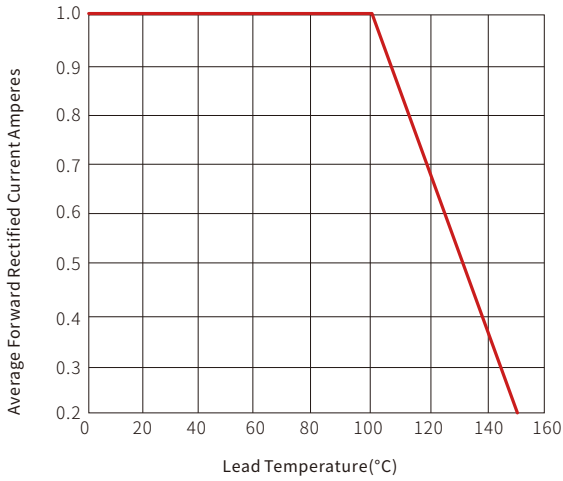
Parameter	Symbol	ES1A	ES1B	ES1C	ES1D	ES1F	ES1G	ES1H	ES1J	Unit	
Marking		ES1A	ES1B	ES1C	ES1D	ES1F	ES1G	ES1H	ES1J		
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	150	200	300	400	500	600		
Maximum RMS voltage	V <sub>RMS</sub>	35	70	105	140	210	280	350	420	V	
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	150	200	300	400	500	600		
Maximum average forward rectified current at T <sub>L</sub> =100°C	I <sub>F(AV)</sub>	1.0								A	
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load per diode	I <sub>FSM</sub>	30.0									
Maximum instantaneous forward voltage at 1.0A	V <sub>F</sub>	0.95			1.30		1.7			V	
Maximum DC reverse current T <sub>A</sub> =25°C at rated DC blocking voltage	T <sub>J</sub> =25°C	5.0								μA	
	T <sub>J</sub> =125°C	500									
Maximum reverse recovery time(Note 1)	T <sub>rr</sub>	35									ns
Typical junction capacitance (Note2)	C <sub>J</sub>	18.0									pF
Typical thermal resistance	R <sub>θJA</sub>	80.0									°C/W
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150								°C	

Note :

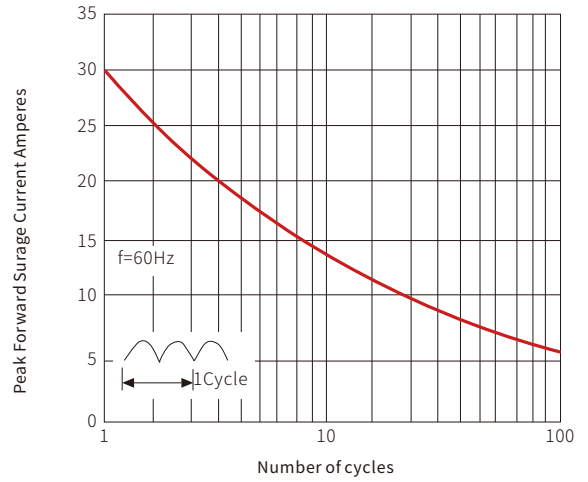
- 1.Reverse recovery time test condition: I<sub>F</sub>=0.5A I<sub>R</sub>=1.0A I<sub>RR</sub>=0.25A
- 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

# CHARACTERISTIC CURVES

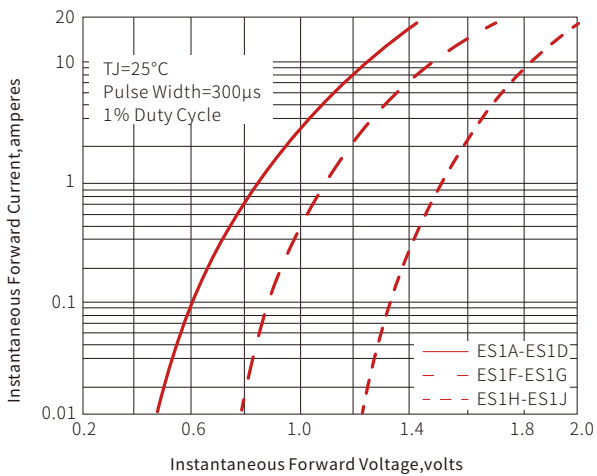
**Fig. 1- Derating Curve Output Rectified Current**



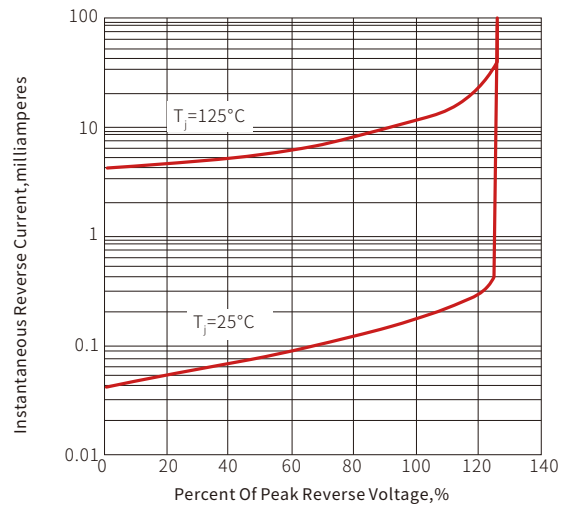
**Fig. 2-maximum Non-repetitive Peak Forward Surge Current Perleg**



**Fig. 3-Typical Forward Voltage Characteristics**

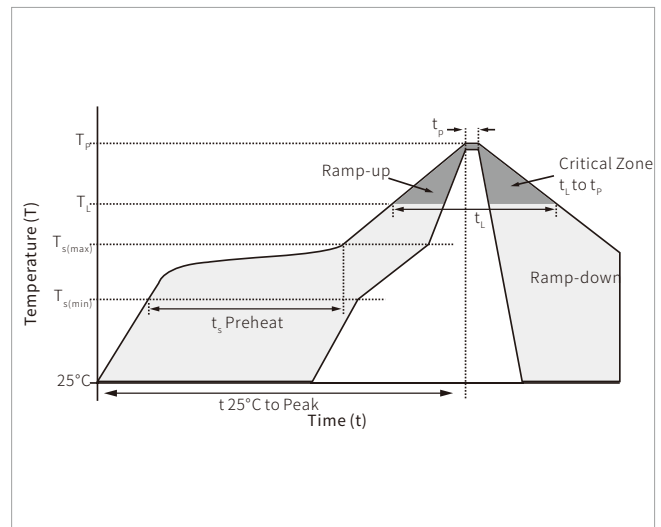


**Fig. 4-Typical Reverse Leakage Characteristics**

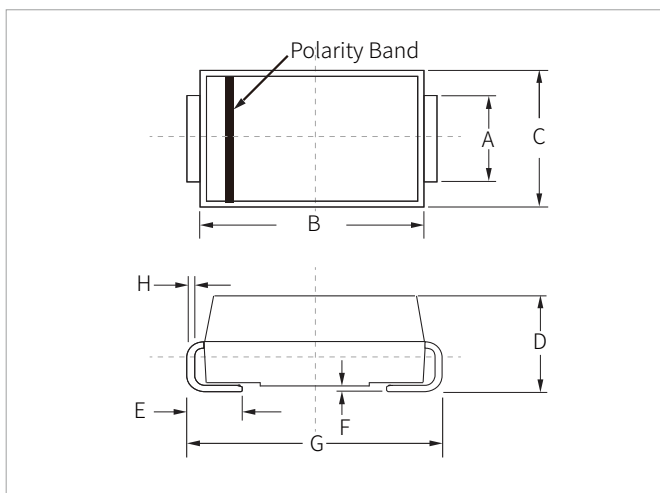


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

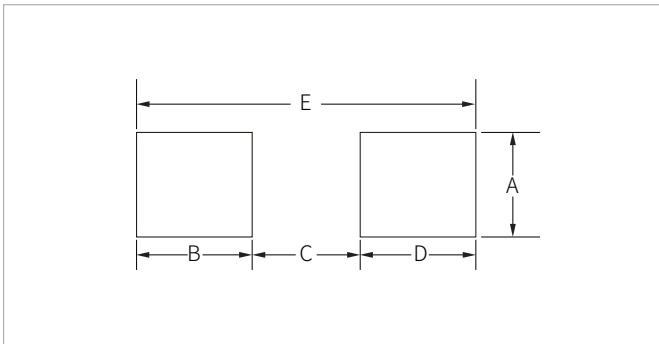


## DO-214AC(SMA) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.20	1.60	0.047	0.063
B	4.20	4.60	0.165	0.181
C	2.40	2.80	0.094	0.110
D	2.00	2.40	0.079	0.094
E	0.76	1.52	0.030	0.060
F	0.02	0.20	0.001	0.008
G	4.85	5.25	0.191	0.207
H	0.15	0.30	0.006	0.012

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.63	-	0.064	-
B	1.45	-	0.057	-
C	-	2.80	-	0.090
D	1.45	-	0.057	-
E	5.28REF		0.208REF	

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
ES1A-ES1J	DO-214AC(SMA)	5000PCS	13"

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Website



Wechat

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